Tflex™ CR200 Series

Gap Filler Material

TWO-PART CURE IN PLACE GAP FILLER

Tflex™ CR200 is a two-part, silicone-based thermal gap filler that has low viscosity prior to curing. Tflex™ CR200 is ideal for applications where large gap tolerances are present. The low viscosity makes it ideal for applications in which the components cannot withstand high pressure during assembly. The mixed material will cure at room temperature or can be accelerated with the addition of heat. The Tflex™ CR200 composition provides excellent thermal performance and compliance.

FEATURES AND BENEFITS

- Soft and compliant transferring little to no pressure between interfaces
- 2.0 W/mK thermal conductivity
- Available in 50cc & 200cc cartridges, and 20 kg pail kits
- Easy to dispense

APPLICATIONS

- Automotive electronics
- LED Lighting
- Graphic chips
- Telecom Base Stations
- Microprocessors

SPECIFICATIONS

	Tflex™ CR200	METHOD
Composition	Two-part, ceramic filled dispensable liquid silicone gap filler	
Color/Part A	Yellow	Visual
Color/Part B	White	Visual
Viscosity before combining (cps)	260,000	ASTM D2196
Density (g/cc)	2.47	Helium Pycnometer
Mix ratio	1.1	
PROPERTIES AFTER CURING		
Thermal Conductivity (W/mK)	2.0	Hot Disk
Hardness (Shore 00): 3 seconds	45	ASTM D2240
Volume Resistivity (Ohm-cm)	10^{13}	ASTM D991
Continuous Use Temperature (°C)	-45 to 200	
Minimum Bondline Thickness (microns)	25.4	
Glass Transition Temperture, Tg (°C)	< -60	ASTM E1356
Flammability	VO	UL 94
CURING PROFILE		
Pot life @ 25°C (minutes)	≥ 60	
Cure @ 25°C (minutes)	300	
Cure @ 100°C (minutes)	2	

OPTIONS

Available in 50 cc & 200 cc cartridges, and 20 kg pail kits
Available with or without beads (8 mils and 10 mils beads)

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